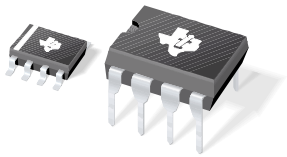


EXTENDED COMMON-MODE RS-485 TRANSCEIVERS

FEATURES

- **Common-Mode Voltage Range (–20 V to 25 V) More Than Doubles TIA/EIA-485 Requirement**
- **Reduced Unit-Load for Up to 256 Nodes**
- **Bus I/O Protection to Over 16-kV HBM**
- **Failsafe Receiver for Open-Circuit, Short-Circuit and Idle-Bus Conditions**
- **Low Standby Supply Current 1-μA Max**
- **More Than 100 mV Receiver Hysteresis**

APPLICATIONS

- **Long Cable Solutions**
  - **Factory Automation**
  - **Security Networks**
  - **Building HVAC**
- **Severe Electrical Environments**
  - **Electrical Power Inverters**
  - **Industrial Drives**
  - **Avionics**

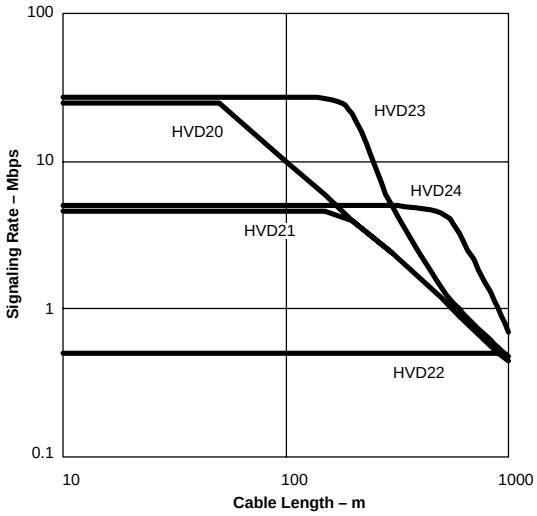
DESCRIPTION

The transceivers in the HVD2x family offer performance far exceeding typical RS–485 devices. In addition to meeting all requirements of the TIA/EIA–485–A standard, the HVD2x family operates over an extended range of common–mode voltage, and has features such as high ESD protection, wide receiver hysteresis, and failsafe operation. This family of devices is ideally suited for long-cable networks, and other applications where the environment is too harsh for ordinary transceivers.

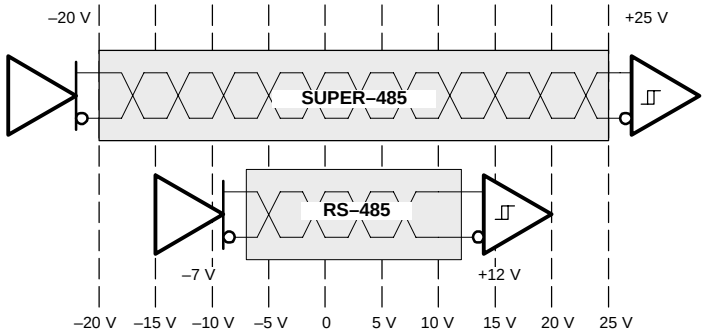
These devices are designed for bidirectional data transmission on multipoint twisted-pair cables. Example applications are digital motor controllers, remote sensors and terminals, industrial process control, security stations, and environmental control systems.

These devices combine a 3-state differential driver and a differential receiver, which operate from a single 5-V power supply. The driver differential outputs and the receiver differential inputs are connected internally to form a differential bus port that offers minimum loading to the bus. This port features an extended common-mode voltage range making the device suitable for multipoint applications over long cable runs.

HVD2x APPLICATION SPACE



HVD2x Devices Operate Over a Wider Common-Mode Voltage Range



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

DESCRIPTION (continued)

The ‘HVD20 provides high signaling rate (up to 25 Mbps) for interconnecting networks of up to 64 nodes.

The ‘HVD21 allows up to 256 connected nodes at moderate data rates (up to 5 Mbps). The driver output slew rate is controlled to provide reliable switching with shaped transitions which reduce high-frequency noise emissions.

The ‘HVD22 has controlled driver output slew rate for low radiated noise in emission-sensitive applications and for improved signal quality with long stubs. Up to 256 ‘HVD22 nodes can be connected at signaling rates up to 500 kbps.

The ‘HVD23 implements receiver equalization technology for improved jitter performance on differential bus applications with data rates up to 25 Mbps at cable lengths up to 160 meters.

The ‘HVD24 implements receiver equalization technology for improved jitter performance on differential bus applications with data rates in the range of 1 Mbps to 10 Mbps at cable lengths up to 1000 meters.

The receivers also include a failsafe circuit that will provide a high-level output within 250 microseconds after loss of the input signal. The most common causes of signal loss are disconnected cables, shorted lines, or the absence of any active transmitters on the bus. This feature prevents noise from being received as valid data under these fault conditions. This feature may also be used for Wired-Or bus signaling.

The SN65HVD2X devices are characterized for operation over the temperature range of –40°C to 85°C.

PRODUCT SELECTION GUIDE

PART NUMBERS	CABLE LENGTH AND SIGNALING RATE(1)	NODES	MARKING
SN65HVD20	Up to 50 m at 25 Mbps	Up to 64	D: VP20 P: 65HVD20
SN65HVD21	Up to 150 m at 5 Mbps (with slew rate limit)	Up to 256	D: VP21 P: 65HVD21
SN65HVD22	Up to1200 m at 500 kbps (with slew rate limit)	Up to 256	D: VP22 P: 65HVD22
SN65HVD23	Up to 160 m at 25 Mbps (with receiver equalization)	Up to 64	D: VP23 P: 65HVD23
SN65HVD24	Up to 500 m at 3 Mbps (with receiver equalization)	Up to 256	D: VP24 P: 65HVD24

(1) Distance and signaling rate predictions based upon Belden 3105A cable and 15% eye pattern jitter.

AVAILABLE OPTIONS

PLASTIC THROUGH-HOLE P–PACKAGE (JEDEC MS-001)	PLASTIC SMALL-OUTLINE(1) D–PACKAGE (JEDEC MS-012)
SN65HVD20P	SN65HVD20D
SN65HVD21P	SN65HVD21D
SN65HVD22P	SN65HVD22D
SN65HVD23P	SN65HVD23D
SN65HVD24P	SN65HVD24D

(1) Add R suffix for taped and reeled carriers.

DRIVER FUNCTION TABLE

HVD20, HVD21, HVD22				HVD23, HVD24			
INPUT	ENABLE	OUTPUTS		INPUT	ENABLE	OUTPUTS	
D	DE	A	B	D	DE	A	B
H	H	H	L	H	H	H	L
L	H	L	H	L	H	L	H
X	L	Z	Z	X	L	Z	Z
X	OPEN	Z	Z	X	OPEN	Z	Z
OPEN	H	H	L	OPEN	H	L	H

H = high level, L= low level, X = don't care, Z = high impedance (off), ? = indeterminate

RECEIVER FUNCTION TABLE

DIFFERENTIAL INPUT $V_{ID} = (V_A - V_B)$	ENABLE $\overline{RE}$	OUTPUT R
$0.2\ V \le V_{ID}$	L	H
$-0.2\ V < V_{ID} < 0.2\ V$	L	See Note A
$V_{ID} \le -0.2\ V$	L	L
X	H	Z
X	OPEN	Z
Open circuit	L	H
Short Circuit	L	H
Idle (terminated) bus	L	H

H = high level, L= low level, X = don't care,
Z = high impedance (off), ? = indeterminate

NOTE A: If the differential input V_{ID} remains within the indeterminate-logic range for more than 250 μs, the integrated failsafe circuitry detects a bus fault, and set the receiver output to a high state. See Figure 15.

POWER DISSIPATION RATINGS

PACKAGE	CIRCUIT BOARD MODEL	$T_A \le 25°C$ POWER RATING	DERATING FACTOR(3) ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING	$T_A = 85°C$ POWER RATING
D	Low-K(1)	710 mW	5.68 mW/°C	455 mW	370 mW
	High-K(2)	1282 mW	10.3 mW/°C	821 mW	667 mW
P	Low-K(1)	984 mW	7.87 mW/°C	630 mW	512 mW
	High-K(2)	1478 mW	11.8 mW/°C	946 mW	768 mW

(1) In accordance with the Low-K thermal metric definitions of EIA/JESD51–3.
(2) In accordance with the High-K thermal metric definitions of EIA/JESD51–7.
(3) This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range unless otherwise noted(1)

			SN65HVD2X
Supply voltage(2), V_{CC}			–0.5 V to 7 V
Voltage at any bus I/O terminal			–27 V to 27 V
Voltage input, transient pulse, A and B, (through 100 Ω, see Figure 16)			–60 V to 60 V
Voltage input at any D, DE or $\overline{RE}$ terminal			–0.5 V to V_{CC}+ 0.5 V
Electrostatic discharge	Human Body Model(3)	A, B, GND	16 kV
		All pins	5 kV
	Charged-Device Model(4)	All pins	1.5 kV
	Machine Model(5)	All pins	200 V
Continuous total power dissipation			See Power Dissipation Rating Table
Junction temperature, T_J			150°C
Storage temperature, T_{stg}			–65°C to 120°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.
(3) Tested in accordance with JEDEC Standard 22, Test Method A114-A.
(4) Tested in accordance with JEDEC Standard 22, Test Method C101.
(5) Tested in accordance with JEDEC Standard 22, Test Method A115-A.

RECOMMENDED OPERATING CONDITIONS

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.5	5	5.5	V
Voltage at any bus I/O terminal	A, B	–20		25	V
High-level input voltage, V_{IH}	D, DE, $\overline{RE}$	2		V_{CC}	V
Low-level input voltage, V_{IL}		0		0.8	
Differential input voltage, V_{ID}	A with respect to B	–25		25	V
Output current	Driver	–110		110	mA
	Receiver	–8		8	
Operating free-air temperature, T_A		–40		85	°C
Junction temperature, T_J		–40		125	°C

DRIVER ELECTRICAL CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)(1)

PARAMETER		TEST CONDITIONS	MIN	TYP(1)	MAX	UNIT
V_{IK}	Input clamp voltage	I_I = –18 mA	–1.5			V
V_O	Open-circuit output voltage	A or B, No load	0		V_{CC}	V
$\|V_{OD(SS)}\|$	Steady-state differential output voltage magnitude	No load (open circuit)	3.3	4.2	V_{CC}	V
		R_L = 54 Ω, See Figure 1	1.8	2.5		
		With common-mode loading, See Figure 2	1.8			
$\Delta\|V_{OD(SS)}\|$	Change in steady-state differential output voltage between logic states	See Figure 1 and Figure 3	–0.1		0.1	V
$V_{OC(SS)}$	Steady-state common-mode output voltage	See Figure 1	2.1	2.5	2.9	V
$\Delta V_{OC(SS)}$	Change in steady-state common-mode output voltage, $V_{OC(H)} - V_{OC(L)}$	See Figure 1 and Figure 4	–0.1		0.1	V
$V_{OC(PP)}$	Peak-to-peak common-mode output voltage, $V_{OC(MAX)} - V_{OC(MIN)}$	R_L = 54 Ω, C_L = 50 pF, See Figure 1 and Figure 4		0.35		V
$V_{OD(RING)}$	Differential output voltage over and under shoot	R_L = 54 Ω, C_L = 50 pF, See Figure 5			10%	
I_I	Input current	D, DE	–100		100	µA
$I_{O(OFF)}$	Output current with power off	V_{CC} < = 2.5 V	See receiver line input current			
I_{OZ}	High impedance state output current	DE at 0 V				
I_{OS}	Short-circuit output current	V_O = –20 V to 25 V, See Figure 9	–250		250	mA
C_{OD}	Differential output capacitance		See receiver C_I			

(1) All typical values are at V_{CC} = 5 V and 25°C.

DRIVER SWITCHING CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP(1)	MAX	UNIT
t_{PLH}	Differential output propagation delay, low-to- high	R_L = 54 Ω, C_L = 50 pF, See Figure 3	HVD20, HVD23	6	10	20	ns
			HVD21, HVD24	20	32	60	
t_{PHL}	Differential output propagation delay, high-to-low		HVD22	160	280	500	
t_r	Differential output rise time	R_L = 54 Ω, C_L = 50 pF, See Figure 3	HVD20, HVD23	2	6	12	ns
			HVD21, HVD24	20	40	60	
t_f	Differential output fall time		HVD22	200	400	600	
t_{PZH}	Propagation delay time, high-impedance-to-high-level output	$\overline{RE}$ at 0 V, See Figure 6	HVD20, HVD23			40	ns
			HVD21, HVD24			100	
t_{PHZ}	Propagation delay time, high-level-output-to-high-impedance		HVD22			300	
t_{PZL}	Propagation delay time, high-impedance-to-low-level output	$\overline{RE}$ at 0 V, See Figure 7	HVD20, HVD23			40	ns
			HVD21, HVD24			100	
t_{PLZ}	Propagation delay time, low-level-output-to-high-impedance		HVD22			300	
$t_{d(standby)}$	Time from an active differential output to standby	$\overline{RE}$ at V_{CC}, See Figure 8				2	µs
$t_{d(wake)}$	Wake-up time from standby to an active differential output					8	µs
$t_{sk(p)}$	Pulse skew $\|t_{PLH} - t_{PHL}\|$	HVD20, HVD23				2	ns
		HVD21, HVD24				6	
		HVD22				50	

(1) All typical values are at V_{CC} = 5 V and 25°C.

RECEIVER ELECTRICAL CHARACTERISTICS

over recommended operating conditions

PARAMETER		TEST CONDITIONS		MIN	TYP(1)	MAX	UNIT
$V_{IT(+)}$	Positive-going differential input voltage threshold	See Figure 10	V_O = 2.4 V, I_O = –8 mA		60	200	mV
$V_{IT(–)}$	Negative-going differential input voltage threshold		V_O = 0.4 V, I_O = 8 mA	–200	–60		
V_{HYS}	Hysteresis voltage ($V_{IT+} – V_{IT–}$)			100	130		mV
$V_{IT(F+)}$	Positive-going differential input failsafe voltage threshold	See Figure 15	V_{CM} = –7 V to 12 V	40	120	200	mV
			V_{CM} = –20 V to 25 V	40	120	250	
$V_{IT(F–)}$	Negative-going differential input failsafe voltage threshold	See Figure 15	V_{CM} = –7 V to 12 V	–40	–120	–200	mV
			V_{CM} = –20 V to 25 V	–40	–120	–250	
V_{IK}	Input clamp voltage	I_I = –18 mA		–1.5			V
V_{OH}	High-level output voltage	V_{ID} = 200 mV, I_{OH} = –8 mA, See Figure 11		4			V
V_{OL}	Low-level output voltage	V_{ID} = –200 mV, I_{OL} = 8 mA, See Figure 11				0.4	V
$I_{I(BUS)}$	Bus input current (power on or power off)	V_I = –7 to 12 V, Other input = 0 V	HVD20, HVD23	–400		500	µA
			HVD21, HVD22, HVD24	–100		125	
		V_I = –20 to 25 V, Other input = 0 V	HVD20, HVD23	–800		1000	
			HVD21, HVD22, HVD24	–200		250	
I_I	Input current	$\overline{RE}$		–100		100	µA
R_I	Input resistance	HVD20, 23		24			kΩ
		HVD21, 22, 24		96			
C_{ID}	Differential input capacitance	V_{ID} = 0.5 + 0.4 sine (2π x 1.5 x 10^6t)				20	pF

(1) All typical values are at 25°C.

RECEIVER SWITCHING CHARACTERISTICS

over recommended operating conditions

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high level output	See Figure 11	HVD20, HVD23		16	35	ns
t_{PHL}	Propagation delay time, high-to-low level output		HVD21, HVD22, HVD24		25	50	
t_r	Receiver output rise time	See Figure 11			2	4	ns
t_f	Receiver output fall time						
t_{PZH}	Receiver output enable time to high level	See Figure 12			90	120	ns
t_{PHZ}	Receiver output disable time from high level				16	35	
t_{PZL}	Receiver output enable time to low level	See Figure 13			90	120	ns
t_{PLZ}	Receiver output disable time from low level				16	35	
$t_{r(standby)}$	Time from an active receiver output to standby	See Figure 14, DE at 0 V				2	µs
$t_{r(wake)}$	Wake-up time from standby to an active receiver output					8	
$t_{sk(p)}$	Pulse skew | $t_{PLH} – t_{PHL}$ |					5	ns
$t_{p(set)}$	Delay time, bus fail to failsafe set	See Figure 15, pulse rate = 1 kHz			250	350	µs
$t_{p(reset)}$	Delay time, bus recovery to failsafe reset					50	ns

SUPPLY CURRENT

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
I_{CC}	Supply current	Driver enabled (DE at V_{CC}), Receiver enabled (RE at 0 V) No load, V_I = 0 V or V_{CC}	HVD20			9	mA
			HVD21			12	
			HVD22			9	
			HVD23			11	
			HVD24			14	
		Driver enabled (DE at V_{CC}), Receiver disabled (RE at V_{CC}) No load, V_I = 0 V or V_{CC}	HVD20			8	mA
			HVD21			11	
			HVD22			8	
			HVD23			9	
			HVD24			12	
		Driver disabled (DE at 0 V), Receiver enabled (RE at 0 V) No load	HVD20			7	mA
			HVD21			8	
			HVD22			7	
			HVD23			9	
			HVD24			10	
		Driver disabled (DE at 0 V) Receiver disabled (RE at V_{CC}) D open	All HVD2x			1	µA

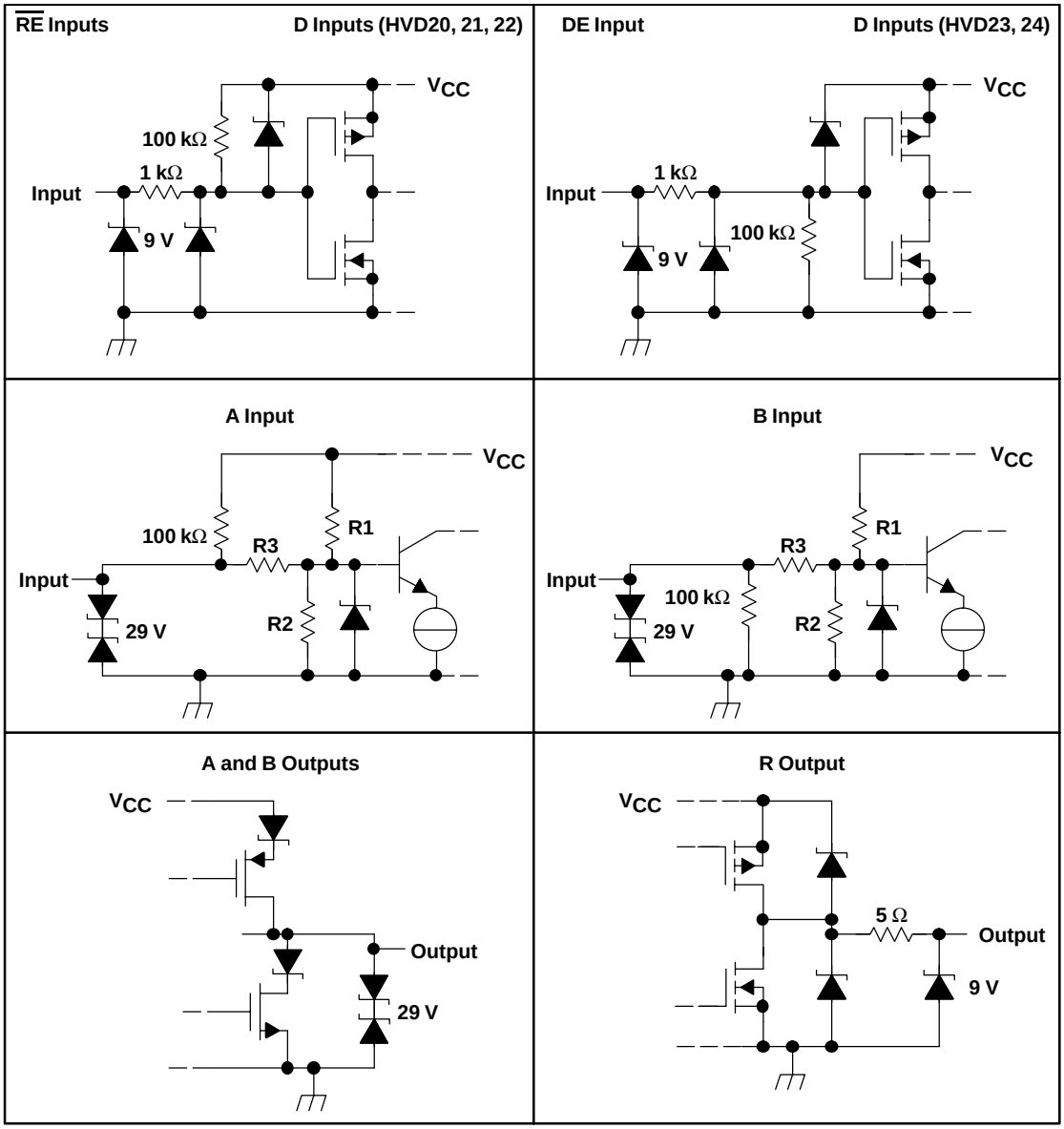
RECEIVER EQUALIZATION CHARACTERISTICS

over recommended operating conditions

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
$t_{j(pp)}$	Peak-to-peak eye-patttern jitter	Pseudo-random NRZ code with a bit pattern length of 2^{16}, See Figure 23	25 Mbps (attenuation similar to 160 m of Belden 3105A)	SN65HVD23			5% t_{ui}(1)	
				SN65HVD24			N/A	
			10 Mbps (attenuation similar to 250 m of Belden 3105A)	SN65HVD23			5% t_{ui}	
				SN65HVD24			5% t_{ui}	
			3 Mbps (attenuation similar to 500 m of Belden 3105A)	SN65HVD23			15% t_{ui}	
				SN65HVD24			5% t_{ui}	
			1 Mbps (attenuation similar to 1000 m of Belden 3105A)	SN65HVD23			25% t_{ui}	
				SN65HVD24			5% t_{ui}	

(1) The unit interval period, t_{ui}, is the inverse of the signaling rate.

EQUIVALENT INPUT AND OUTPUT SCHEMATIC DIAGRAMS



	R1/R2	R3
HVD20, 23	9 kΩ	45 kΩ
HVD21, 22, 24	36 kΩ	180 kΩ

PARAMETER MEASUREMENT INFORMATION

NOTE:

Test load capacitance includes probe and jig capacitance (unless otherwise specified).

Signal generator characteristics: rise and fall time < 6 ns, pulse rate 100 kHz, 50% duty cycle, Z_O = 50 Ω (unless otherwise specified)

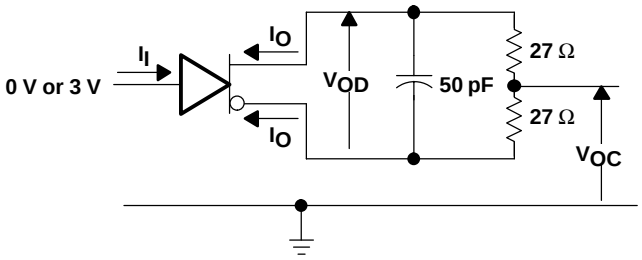


Figure 1. Driver Test Circuit, V_{OD} and V_{OC} Without Common-Mode Loading

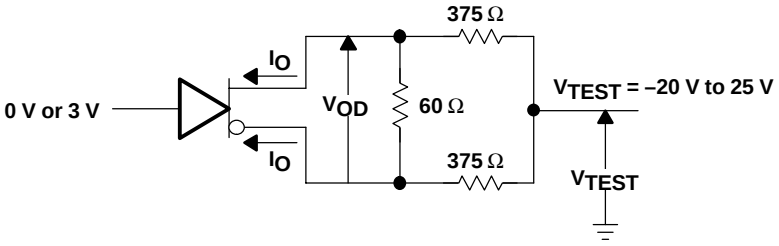


Figure 2. Driver Test Circuit, V_{OD} With Common-Mode Loading

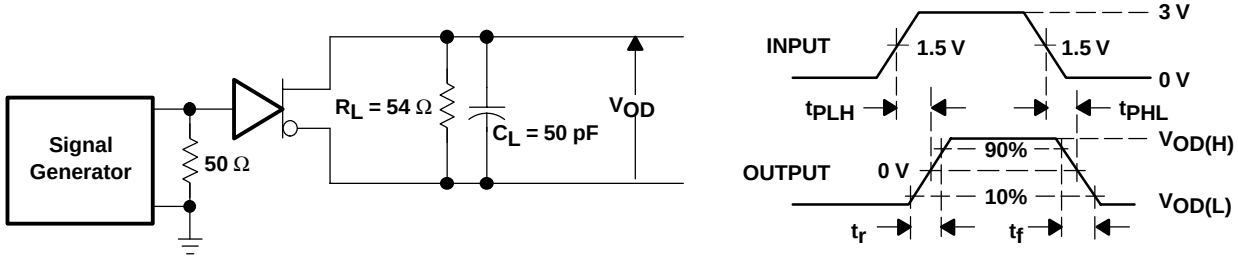


Figure 3. Driver Switching Test Circuit and Waveforms

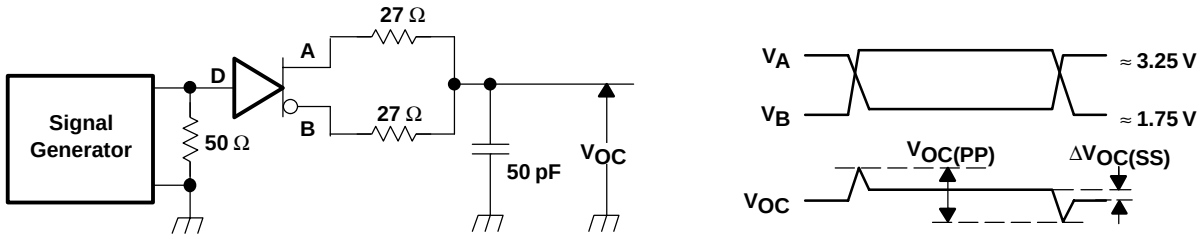
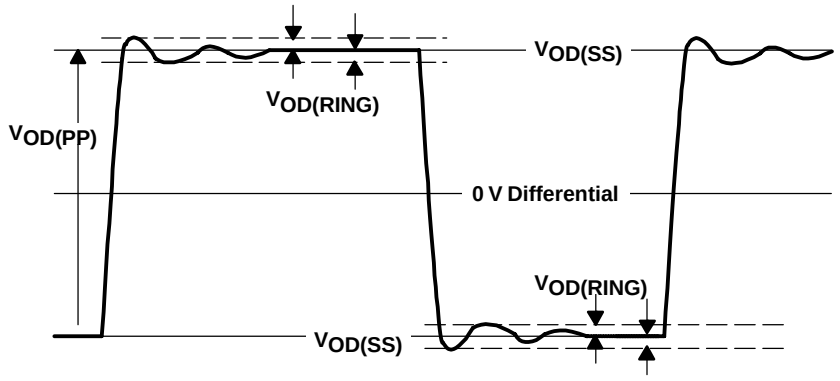


Figure 4. Driver V_{OC} Test Circuit and Waveforms



NOTE: $V_{OD(RING)}$ is measured at four points on the output waveform, corresponding to overshoot and undershoot from the $V_{OD(H)}$ and $V_{OD(L)}$ steady state values.

Figure 5. $V_{OD(RING)}$ Waveform and Definitions

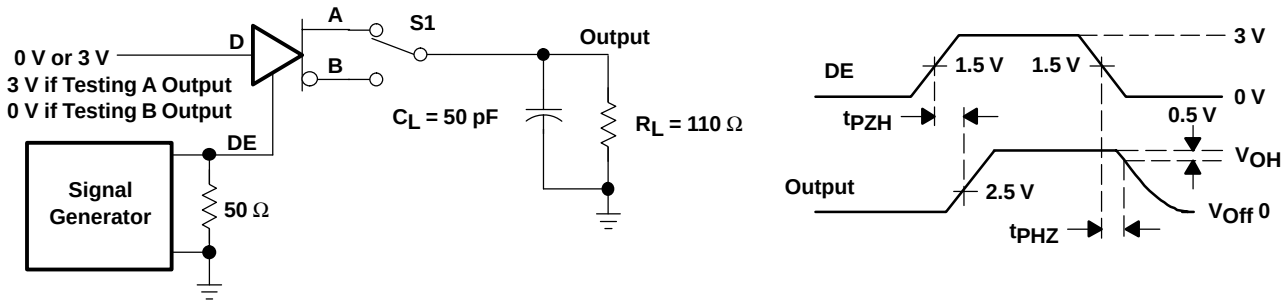


Figure 6. Driver Enable/Disable Test, High Output

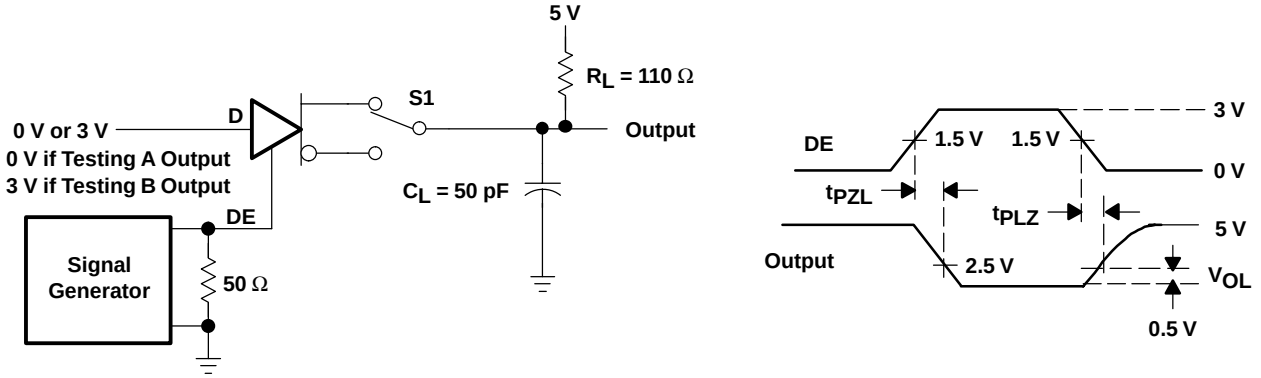


Figure 7. Driver Enable/Disable Test, Low Output

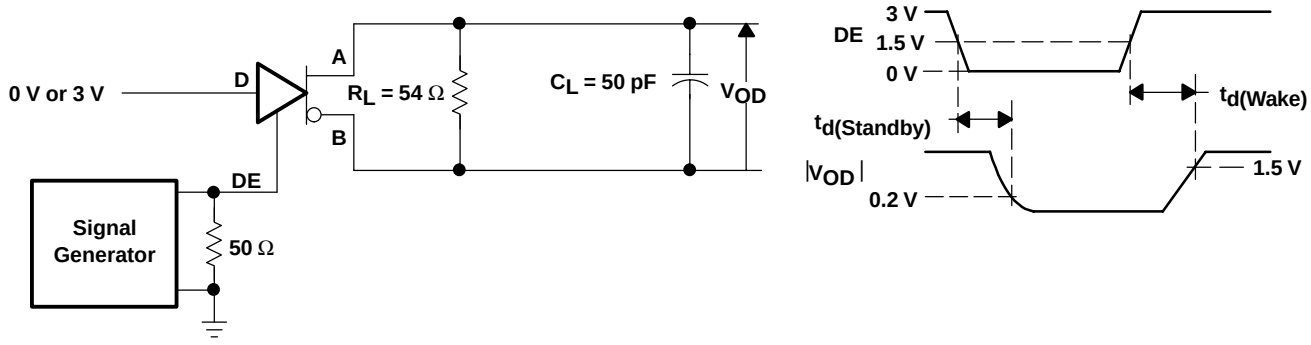


Figure 8. Driver Standby/Wake Test Circuit and Waveforms

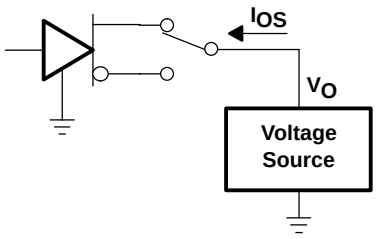


Figure 9. Driver Short-Circuit Test

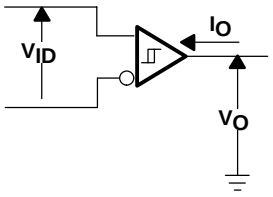


Figure 10. Receiver DC Parameter Definitions

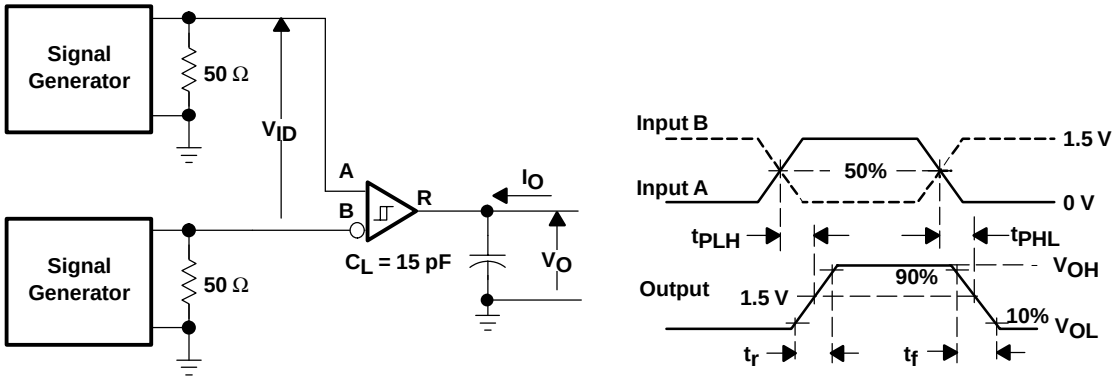


Figure 11. Receiver Switching Test Circuit and Waveforms

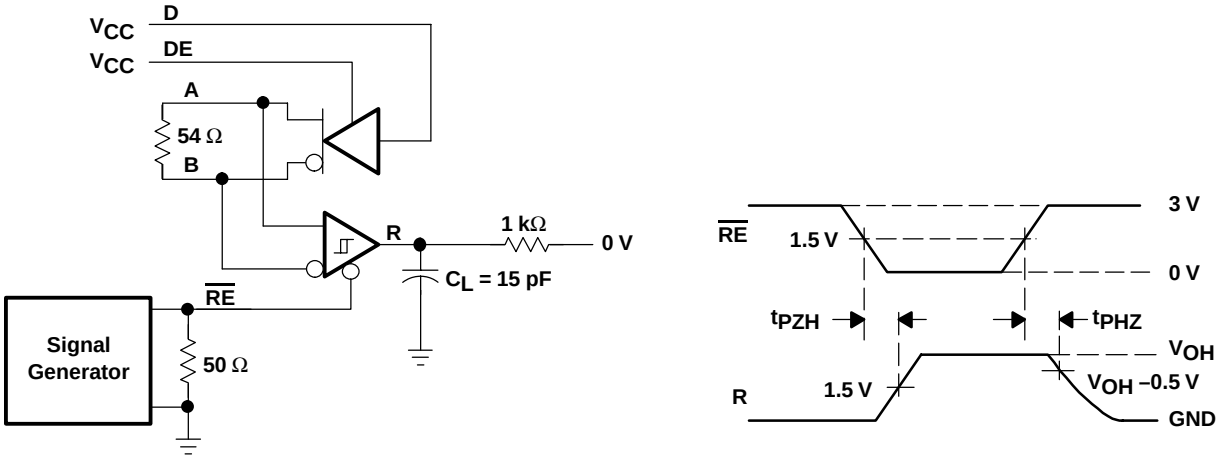


Figure 12. Receiver Enable Test Circuit and Waveforms, Data Output High

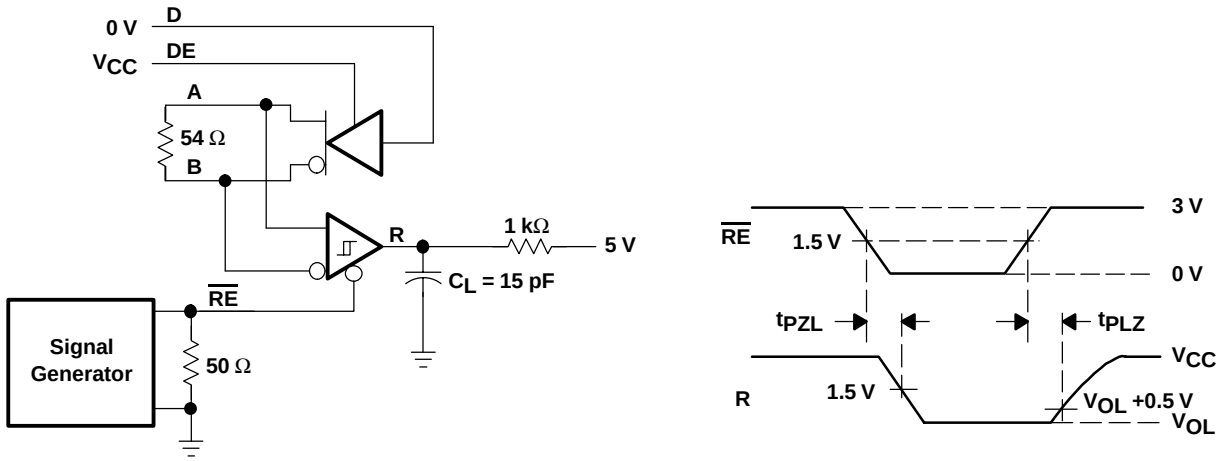


Figure 13. Receiver Enable Test Circuit and Waveforms, Data Output Low

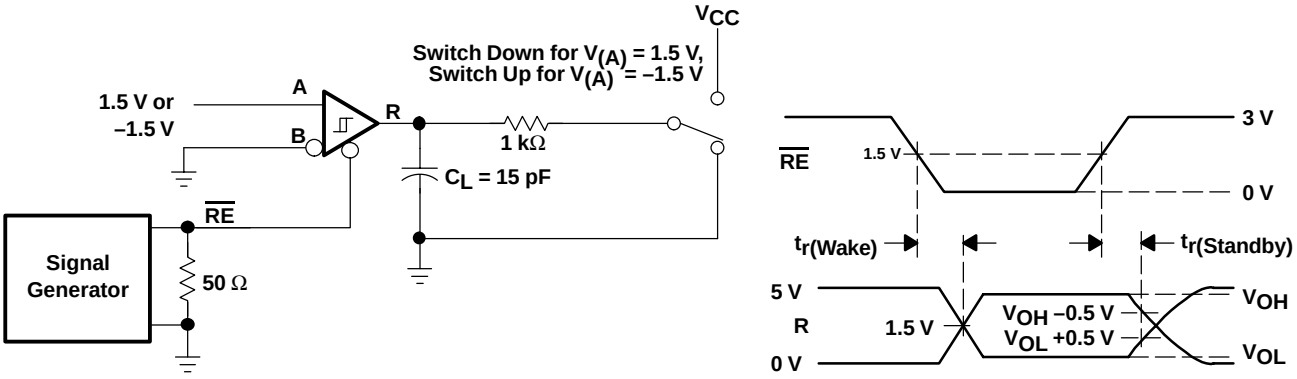


Figure 14. Receiver Standby and Wake Test Circuit and Waveforms

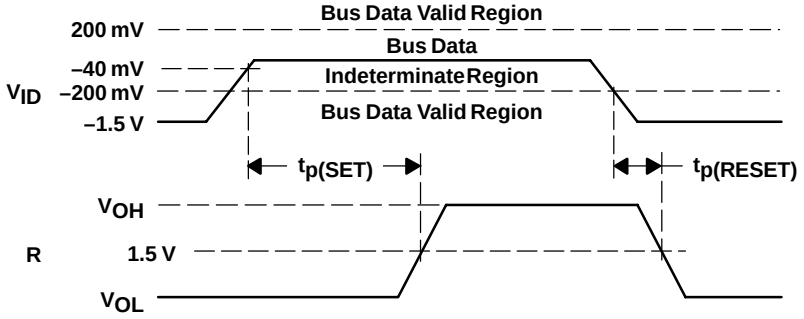


Figure 15. Receiver Active Failsafe Definitions and Waveforms

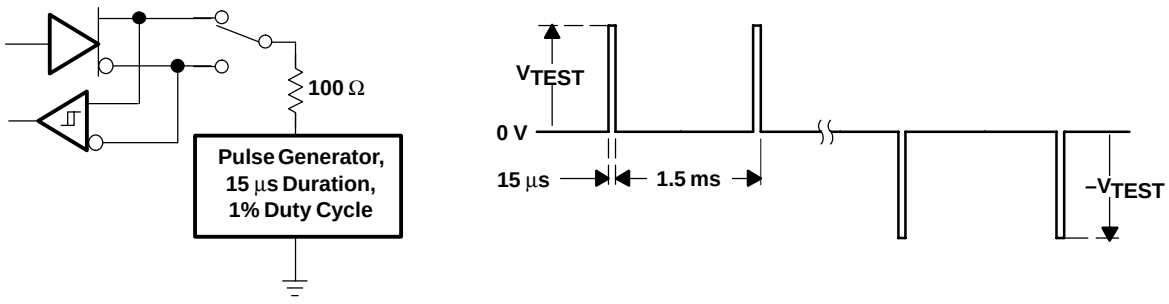
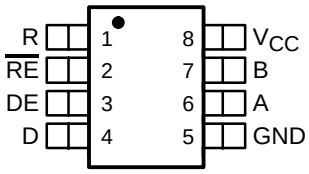


Figure 16. Test Circuit and Waveforms, Transient Over-Voltage Test

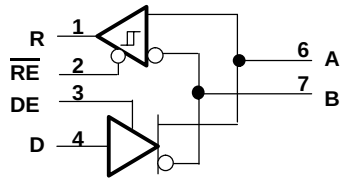
PIN ASSIGNMENTS

D or P PACKAGE
(TOP VIEW)



LOGIC DIAGRAM

POSITIVE LOGIC



TYPICAL CHARACTERISTICS

HVD20, HVD23
BUS PIN CURRENT
vs
BUS PIN VOLTAGE

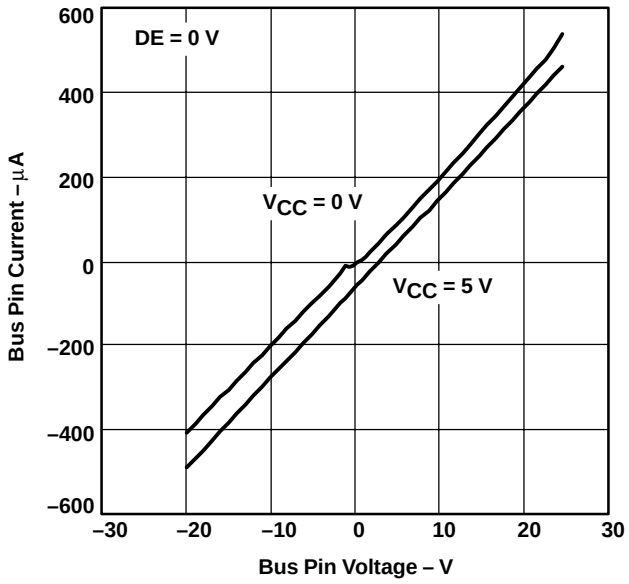


Figure 17

HVD21, HVD22, HVD24
BUS PIN CURRENT
vs
BUS PIN VOLTAGE

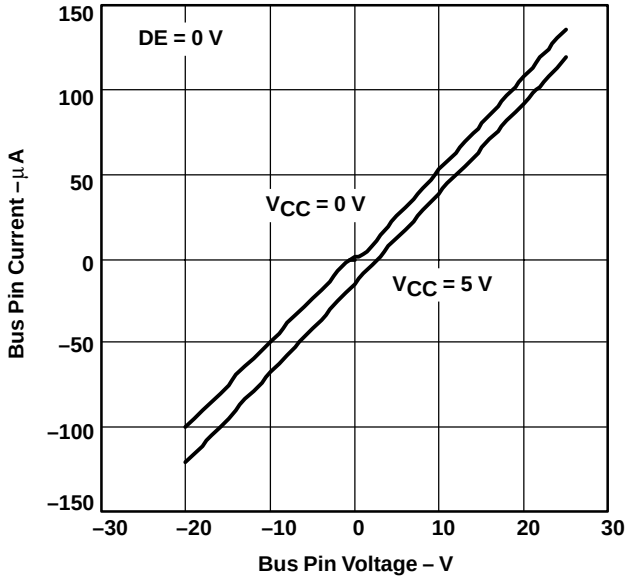


Figure 18

SUPPLY CURRENT
vs
SIGNALING RATE

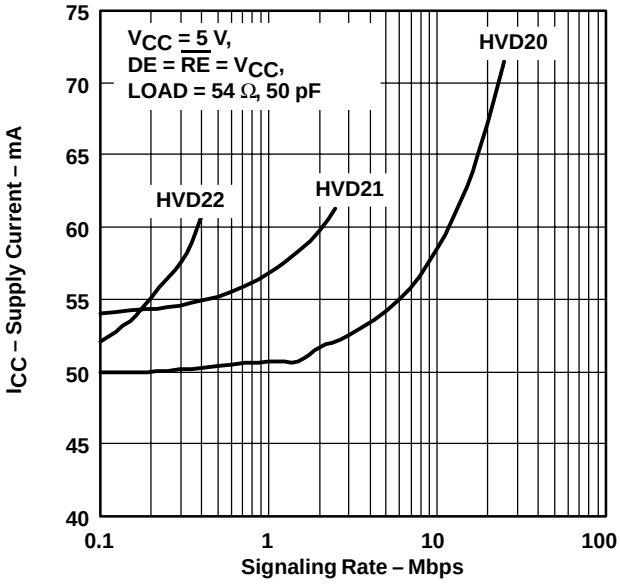


Figure 19

DRIVER DIFFERENTIAL OUTPUT VOLTAGE
vs
DRIVER LOAD CURRENT

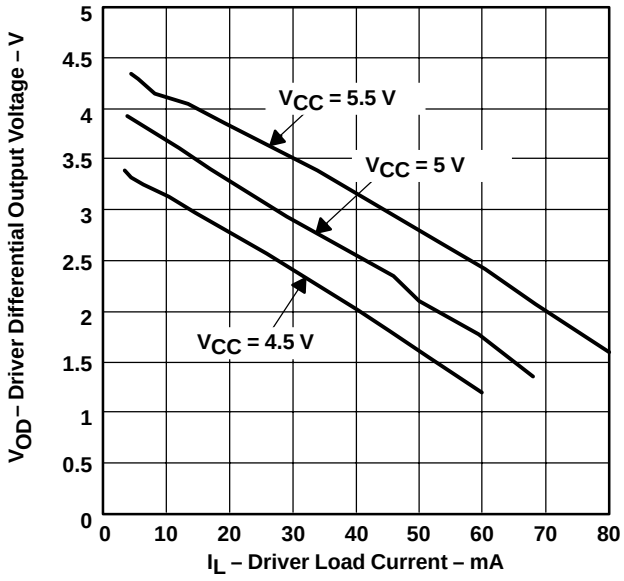


Figure 20

RECEIVER OUTPUT VOLTAGE
vs
DIFFERENTAL INPUT VOLATGE

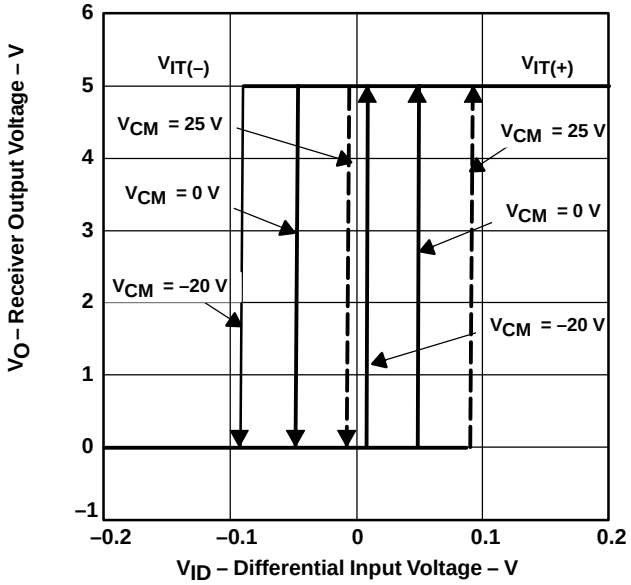


Figure 21

APPLICATION INFORMATION

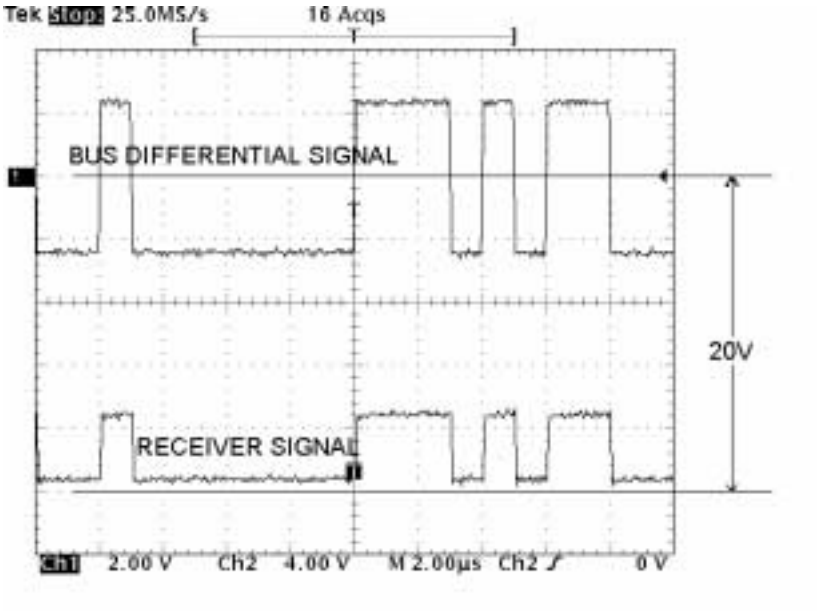


Figure 22. HVD22 Receiver Operation With 20 V Offset on Input Signal

$H(s) = k_0\left[\left(1-k_1\right)+\frac{k_1p_1}{\left(s+p_1\right)}\right]\left[\left(1-k_2\right)+\frac{k_2p_2}{\left(s+p_2\right)}\right]\left[\left(1-k_3\right)+\frac{k_3p_3}{\left(s+p_3\right)}\right]$	k0 (DC loss)	p1 (MHz)	k1	p2 (MHz)	k2	p3 (MHz)	k3
Similar to 160m of Belden 3105A	0.95	0.25	0.3	3.5	0.5	15	1
Similar to 250m of Belden 3105A	0.9	0.25	0.4	3.5	0.7	12	1
Similar to 500m of Belden 3105A	0.8	0.25	0.6	2.2	1	8	1
Similar to 1000m of Belden 3105A	0.6	0.3	1	3	1	6	1

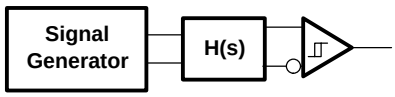


Figure 23. Cable Attenuation Model for Jitter Measurements

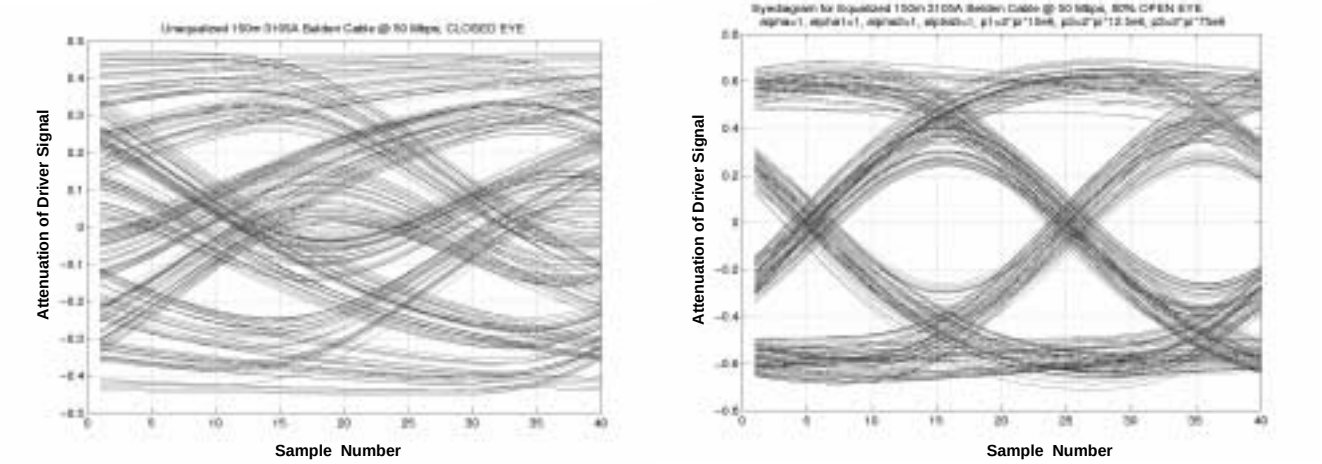


Figure 24. Performance at 50 Mbps Signaling Rate Over 150 Meters Cable, Before and After Receiver Equalization (Preview)

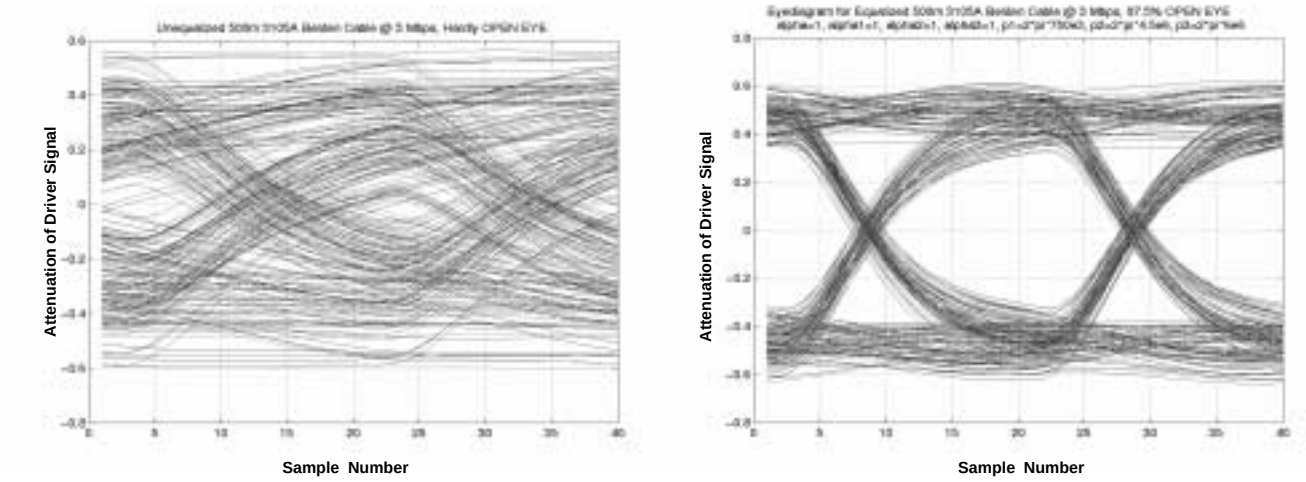
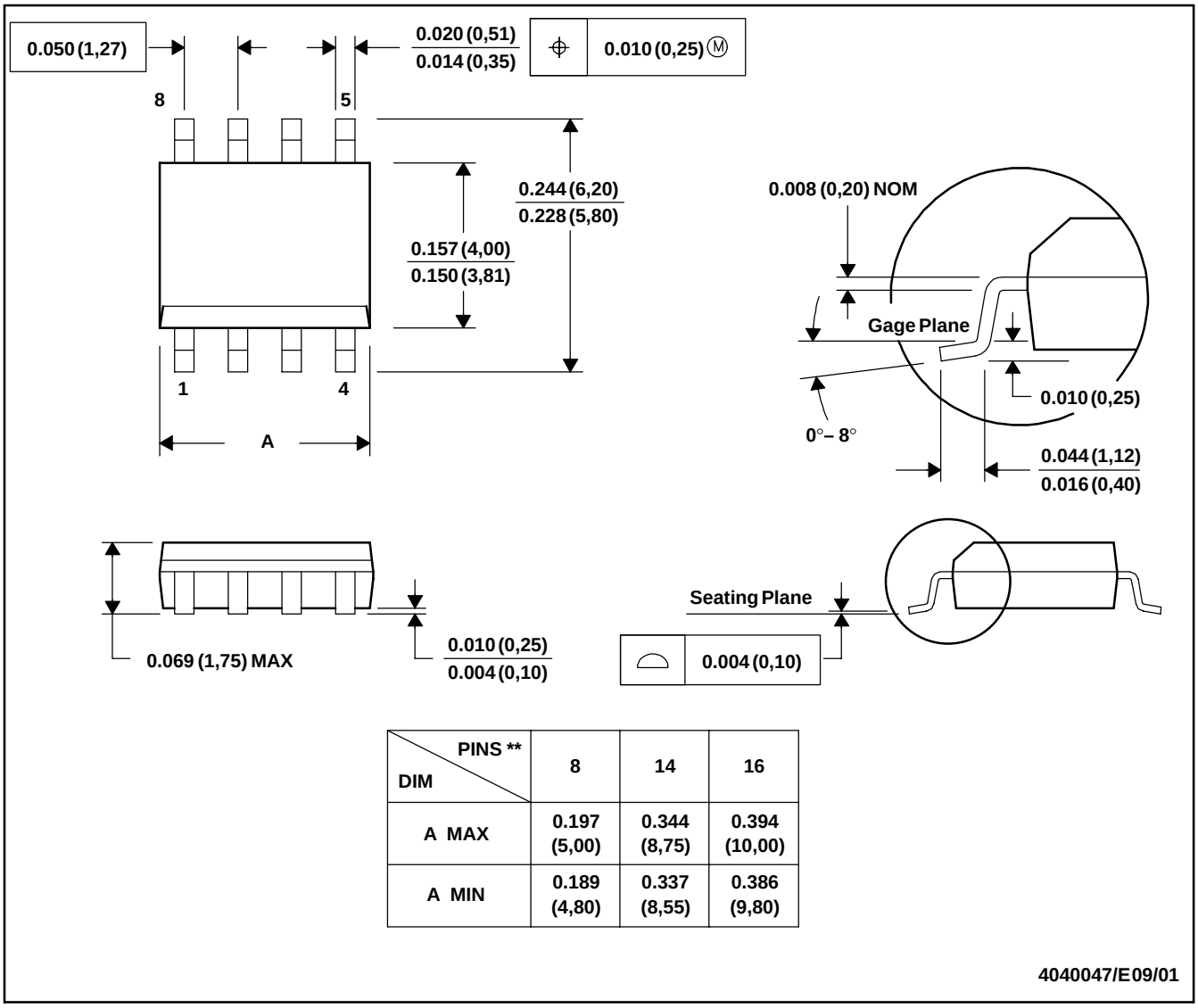


Figure 25. Performance at 3 Mbps Signaling Rate Over 500 Meters Cable, Before and After Receiver Equalization (Preview)

MECHANICAL DATA

D (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

8 PINS SHOWN



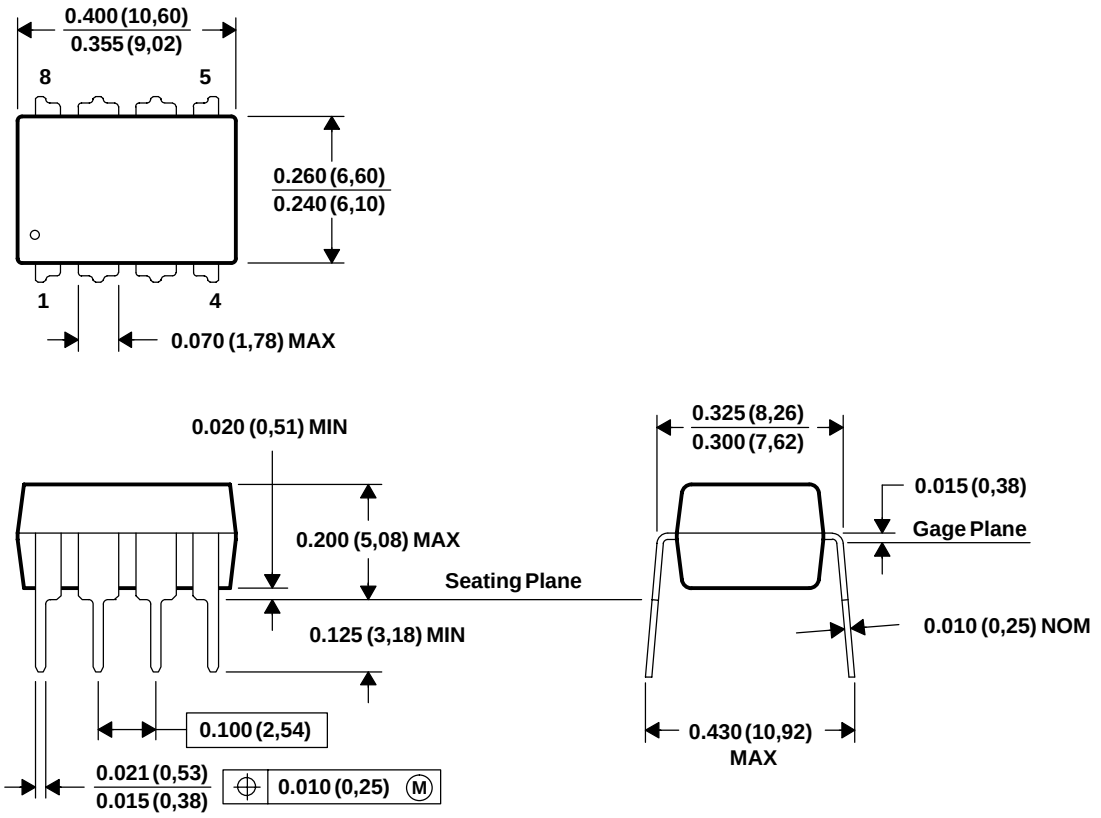
DIM \ PINS **	8	14	16
A MAX	0.197 (5,00)	0.344 (8,75)	0.394 (10,00)
A MIN	0.189 (4,80)	0.337 (8,55)	0.386 (9,80)

4040047/E 09/01

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-012

MECHANICAL DATA

P (R-PDIP-T8) **PLASTIC DUAL-IN-LINE**



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-001

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